

**A METHOD FOR ALLOWING
A STABLE POWER TRANSMISSION
INTO A PLASMA PROCESSING CHAMBER**

ABSTRACT OF THE DISCLOSURE

A method of processing a metal layer on a substrate. The method comprises disposing the substrate in a chamber having a dielectric member and processing gas. An interior surface of the dielectric member is heated to a temperature above about 150°C and the metal layer is processed when processing power is passed through the heated dielectric member. Heating of the interior surface of the dielectric member essentially prevents deposits from forming on the interior surface and allows a stable power transmission through the dielectric member.